

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Tarak A. Railkar	01/27/2009
Steven D. Cate	02/02/2009
RECEIVING PARTY DATA	
Name:	Maxim Integrated Products, Inc.
Street Address:	120 San Gabriel Drive
City:	Sunnyvale
State/Country:	CALIFORNIA
Postal Code:	94086
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12364452
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ATTORNEY DOCKET NUMBER:	20046-1427
NAME OF SUBMITTER:	Aimee S, Marth

Total Attachments: 4
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Title: THERMALLY ENHANCED SEMICONDUCTOR PACKAGE
Inventor: Tarak A. Railkar & Steven D. Cate
Filed: February 2, 2009
Serial Number: 12/364,452
Client Docket No.: MAXM-0546
Attorney Docket No.: 20046-1427

ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, the individual(s) named below (hereinafter "INVENTOR" whether singular or plural) has sold, assigned, transferred, and set over, and hereby sells, assigns, transfers and sets over, to Maxim Integrated Products, Inc., a corporation of the State of Delaware, having a place of business at 120 San Gabriel Drive, Sunnyvale, CA 94086("ASSIGNEE"), for itself and its successors, transferees, and assignees, the following:

1. The full and exclusive worldwide right, title, and interest in and to all inventions and improvements ("SUBJECT MATTER") that are disclosed in the U.S. patent application, entitled "THERMALLY ENHANCED SEMICONDUCTOR PACKAGE" ("APPLICATION"),

which is a provisional application

- bearing Application No. _____, and filed on _____;
 to be filed herewith; or

which is a non-provisional application

- bearing Application No. 12/364,452, and filed on February 2, 2009;
 to be filed herewith;
 having an oath or declaration executed on the same date as this Assignment;
 having an oath or declaration executed on a different date than this Assignment.

2. The entire worldwide right, title, and interest in and to the APPLICATION and all applications claiming priority to the APPLICATION or having related SUBJECT MATTER to the APPLICATION, including all such design, utility, divisional, continuation, substitute, renewal, reissue, international, or other related applications and all rights of priority in the APPLICATION, together with all rights to recover damages for infringement.

INVENTOR hereby authorizes and requests the Commissioner of the U.S. Patent and Trademark Office, and Patent Office Officials in all foreign countries, to issue to the ASSIGNEE any and all patents which may be granted from the APPLICATION.

INVENTOR will, without further consideration, communicate to the ASSIGNEE any facts known to the INVENTOR regarding the SUBJECT MATTER, testify in any legal proceeding, sign all lawful papers, execute all oaths, assignments, powers of attorney, applications and any other paper desired by ASSIGNEE to obtain, perfect, or secure to ASSIGNEE any and all of the

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rights, titles and interests herein conveyed, and to maintain, enforce, and defend these rights, titles and interests in the United States and all foreign countries. INVENTOR further agrees to provide any successor, assign, or legal representative of ASSIGNEE with the benefits and assistance provided to ASSIGNEE herein.

INVENTOR represents that the INVENTOR, at the time of the execution of this Assignment, is the sole and lawful owner of the entire rights, titles and interests in and to the SUBJECT MATTER as set forth in the APPLICATION, and that the SUBJECT MATTER is unencumbered, and that the INVENTOR has good and full right and lawful authority to sell and convey the SUBJECT MATTER in the manner herein set forth.

INVENTOR covenants with ASSIGNEE that the INVENTOR has not made and will not hereafter make any assignment, grant, mortgage, license or other agreement affecting the rights, titles, and interests herein conveyed.

INVENTOR agrees to, and hereby acknowledges, that the ASSIGNEE may apply for and receive patents related to the APPLICATION or SUBJECT MATTER.

INVENTOR grants the attorney of record for the APPLICATION the power to insert on this Assignment any further identification, including the application number and filing date, which may be necessary or desirable to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

This Assignment may be executed in one or more counterparts, each of which shall be deemed an original and all of which may be taken together as one and the same Assignment. Two inventor/assignor signature blocks are located on the following pages.

Title: THERMALLY ENHANCED SEMICONDUCTOR PACKAGE
Inventor: Tarak A. Railkar & Steven D. Cate
Filed: Feb 2, 2009
Serial Number: 12/364,452
Client Docket No.: MAXM-0546
Attorney Docket No.: 20046-1427

INVENTOR Name: Tarak A. Railkar

INVENTOR Address: 1117 Parkview Lane

Plano, TX 75075

Date of Signature: January 27, 2009

Tarak A. Railkar

[INVENTOR Signature]

Witnessed by: Eden Chen

Print Name

Signature: Eden Chen

State of _____)

County of _____)

On _____, before me _____ personally appeared
[Date] [Name and Title of Officer]

_____, who proved to me on the basis of satisfactory evidence to be the
[INVENTOR]

person(s) whose name(s) is/are subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of _____ that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.

Signature _____


(Seal)

Title: THERMALLY ENHANCED SEMICONDUCTOR PACKAGE
Inventor: Tarak A. Railkar & Steven D. Cate
Filed: February 2, 2009
Serial Number: 12/364,452
Client Docket No.: MAXM-0546
Attorney Docket No.: 20046-1427

INVENTOR Name: Steven D. Cate

INVENTOR Address: 829 Echo Drive
Los Altos, CA 94024

Date of Signature: 2/2/09


[INVENTOR Signature]

Witnessed by: _____
Print Name

Signature: _____

State of _____)
County of _____)

On _____, before me _____ personally appeared
[Date] [Name and Title of Officer]

_____, who proved to me on the basis of satisfactory evidence to be
the

[INVENTOR]
person(s) whose name(s) is/are subscribed to the within instrument and acknowledged to me
that he/she/they executed the same in his/her/their authorized capacity(ies), and that by
his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the
person(s) acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of _____ that the
foregoing paragraph is true and correct.

WITNESS my hand and official seal.

Signature _____ (Seal)